



# SPECIFICATION

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor

- Samsung P/N : [CL31B475KPHNNWE](#)
- Description : CAP, 4.7 $\mu$ F, 10V,  $\pm 10\%$ , X7R, 1206

## A. Samsung Part Number

CL 31 B 475 K P H N N W E  
 ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

① Series	Samsung Multi-layer Ceramic Capacitor													
② Size	1206 (inch code)			L: 3.2 $\pm 0.2$ mm			W: 1.6 $\pm 0.2$ mm							
③ Dielectric	X7R				⑧ Inner electrode	Ni								
④ Capacitance	4.7 $\mu$ F				Termination	Cu								
⑤ Capacitance tolerance	$\pm 10\%$				Plating	Sn 100% (Pb Free)								
⑥ Rated Voltage	10 V				⑨ Product	Normal								
⑦ Thickness	1.6 $\pm 0.2$ mm				⑩ Special	Product for Network application								
					⑪ Packaging	Embossed Type, 7" reel								

## B. Samsung Reliability Test and Judgement condition

	Performance	Test condition	
Capacitance	Within specified tolerance	1kHz $\pm 10\%$	1.0 $\pm 0.2$ Vrms
Tan $\delta$ (DF)	0.05 max.		
Insulation Resistance	10,000Mohm or 100Mohm $\cdot\mu$ F Whichever is Smaller	Rated Voltage	60~120 sec.
Appearance	No abnormal exterior appearance	Microscope ( $\times 10$ )	
Withstanding Voltage	No dielectric breakdown or mechanical breakdown	250% of the rated voltage	
Temperature Characteristics	X7R (From -55°C to 125°C, Capacitance change should be within $\pm 15\%$ )		
Adhesive Strength of Termination	No peeling shall be occur on the terminal electrode	500g·F, for 10 $\pm 1$ sec.	
Bending Strength	Capacitance change : within $\pm 12.5\%$	Bending to the limit (1mm) with 1.0mm/sec.	
Solderability	More than 75% of terminal surface is to be soldered newly	SnAg3.0Cu0.5 solder 245 $\pm 5$ °C, 3 $\pm 0.3$ sec. (preheating : 80~120 °C for 10~30sec.)	
Resistance to Soldering heat	Capacitance change : within $\pm 7.5\%$ Tan $\delta$ , IR : initial spec.	Solder pot : 270 $\pm 5$ °C, 10 $\pm 1$ sec.	

	Performance	Test condition
<b>Vibration Test</b>	Capacitance change : within $\pm 5\%$ Tan $\delta$ , IR : initial spec.	Amplitude : 1.5mm From 10Hz to 55Hz (return : 1min.) 2hours $\times$ 3 direction (x, y, z)
<b>Moisture Resistance</b>	Capacitance change : within $\pm 12.5\%$ Tan $\delta$ : 0.075 max IR : 500Mohm or $25\text{Mohm} \cdot \mu\text{F}$ Whichever is Smaller	With rated voltage 40 $\pm 2$ °C, 90~95%RH, 500+12/-0hrs
<b>High Temperature Resistance</b>	Capacitance change : within $\pm 12.5\%$ Tan $\delta$ : 0.075 max IR : 1000Mohm or $50\text{Mohm} \cdot \mu\text{F}$ Whichever is Smaller	With 200% of the rated voltage Max. operating temperature 1000+48/-0hrs
<b>Temperature Cycling</b>	Capacitance change : within $\pm 7.5\%$ Tan $\delta$ , IR : initial spec.	1 cycle condition Min. operating temperature $\rightarrow$ 25 °C $\rightarrow$ Max. operating temperature $\rightarrow$ 25 °C  5 cycle test

**C. Recommended Soldering method :**

Reflow ( Reflow Peak Temperature : 260+0/-5 °C, 10sec. Max )

\* For the more detail Specification, Please refer to the Samsung MLCC catalogue.